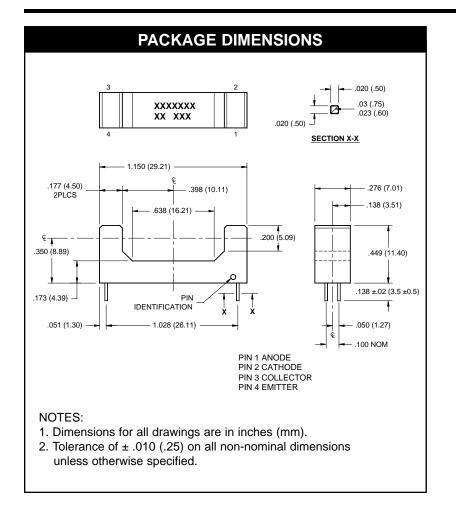
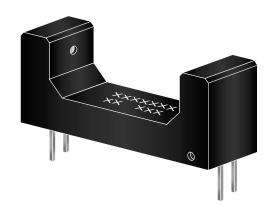
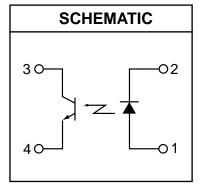




QVL21653







DESCRIPTION

The QVL21653 consists of an infrared light emitting diode coupled to an NPN silicon phototransistor packaged into an injection molded housing. The housing is designed for wide gap, non contact sensing.

FEATURES

- 20 mm wide gap
- PC Board mount
- .060" apertures
- Sensor filter to attenuate visible light



SLOTTED OPTICAL SWITCH

QVL21653

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise specified)							
Parameter	Symbol	Rating	Unit				
Operating Temperature	T _{OPR}	-40 to +85	°C				
Storage Temperature	T _{STG}	T _{STG} -40 to +85					
Soldering Temperature (Iron)(2,3 and 4)	T _{SOL-I}	240 for 5 sec	°C				
Soldering Temperature (Flow)(2 and 3)	T _{SOL-F}	260 for 10 sec	°C				
INPUT (EMITTER) Continuous Forward Current	lF	50	mA				
Reverse Voltage	V _R	6	V				
Power Dissipation (1)	P _D	100	mW				
OUTPUT (SENSOR) Collector to Emitter Voltage	V _{CEO}	30	V				
Emitter to Collector Voltage	V _{ECO}	4.5	V				
Collector Current	I _C	20	mA				
Power Dissipation ⁽¹⁾	P_{D}	150	mW				

NOTES:

- 1. Derate power dissipation linearly 1.67 mW/°C above 25°C.
- 2. RMA flux is recommended.
- 3. Methanol or isopropanol alcohols are recommended as cleaning agents.
- 4. Soldering iron tip 1/16" (1.6mm) minimum from housing.

PARAMETER	TEST CONDITIONS	SYMBOL	MIN	TYP	MAX	UNITS
INPUT (EMITTER)	J 00 A	VF	_	_	1.7	V
Forward Voltage	I _F = 20 mA					
Reverse Leakage Current	V _R = 5 V	I _R	_	_	100	μΑ
OUTPUT (SENSOR)	1 100 1	BV _{ECO}	5	_	_	V
Emitter to Collector Breakdown	$I_{E} = 100 \mu A$					
Collector to Emitter Breakdown	I _C = 1 mA	BV _{CEO}	30	_		V
Collector to Emitter Leakage	V _{CE} = 10 V	I _{CEO}	_	_	100	nA
COUPLED	1 00 = 1 1/2 5 1/	Ic(on)	100		_	μΑ
On-State Collector Current	$I_F = 20 \text{ mA}, V_{CE} = 5 \text{ V}$					
Saturation Voltage	$I_{\rm F} = 20 \text{ mA}, I_{\rm C} = 50 \mu\text{A}$	VCE(SAT)	_	_	0.5	V



SLOTTED OPTICAL SWITCH

QVL21653

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